

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Lee-Sheng Yen	07/12/2010
RECEIVING PARTY DATA	
Name:	ADVANCE MATERIALS CORPORATION
Street Address:	No.498-2, Sec.2, Nan San Rd. Luchu
City:	Taoyuan
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12835746
CORRESPONDENCE DATA	
Fax Number: (703)997-4517 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 3027291562 Email: Patent.admin.uspto.cr@naipo.com Correspondent Name: WINSTON HSU Address Line 1: P.O.BOX 506 Address Line 4: Merrifield, VIRGINIA 22116	
ATTORNEY DOCKET NUMBER:	AMOP0003USA
NAME OF SUBMITTER:	Shelley Kuo
Total Attachments: 2 source=889059#page1.tif source=889059#page2.tif	

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 REEL: 024679 FRAME: 0477

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Docket No AMOP0003USA

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Lee-Sheng Yen Nationality: TW

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: ADVANCE MATERIALS CORPORATION

Address: No.498-2, Sec.2, Nan San Rd. Luchu, Taoyuan 338, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"CIRCUIT BOARD STRUCTURE, PACKAGING STRUCTURE AND METHOD FOR
MAKING THE SAME"

Which is found in :

- (a) + U.S. patent application executed on even date
(b) _____ U.S. patent application executed on _____
(c) _____ U.S. application serial no. _____
(d) _____ patent no. _____ issued _____

NPO#AMO-P0003-USA:0
CUST#

Assignment, Page 1 of 2

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and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment:

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this July 12, 2010 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Lee-Sheng Yen

Signature of INVENTOR

